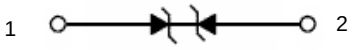
Transient Voltage Suppressors for ESD Protection

FEATURES:

- Low Leakage
- Response Time is Typically < 1 ns
- IEC61000−4−2 Level 4 ESD Protection
- These are Pb−Free Devices
- We declare that the material of product compliance with RoHS requirements and Halogen Free.

Circuit Diagram & Pin Configuration:

SOD-882



DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
TESDN051BD82	AK	10000/Tape&Reel

MAXIMUM RATINGS

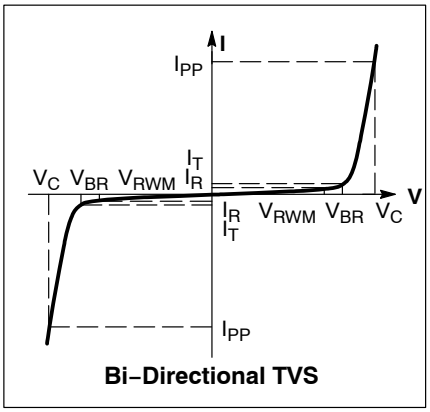
Rating	Symbol	Value	Unit
IEC 61000-4-2 (ESD) Air discharge Contact discharge		±25 ±20	kV kV
Total Power Dissipation on FR-5 Board (Note 1) @ T_A=25	PD	200	mW
Junction and Storage Temperature Range	TJ,TSTG	-55 to 150	
Lead Solder Temperature – Maximum (10 Second Duration)	TL	260	

Stresses exceeding Maximum Ratings may damage the device. Maximum Rating are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 = 1.0*0.75*0.62 in.

ELECTRICAL CHARACTERISTICS
(T_A = 25°C unless otherwise noted)

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
P_{pk}	Peak Power Dissipation
C	Capacitance @ V_R = 0 and f = 1.0 MHz



ELECTRICAL CHARACTERISTICS

Device	V_{RWM} (V)	I_{R1}(μA) @ V_{RWM}	I_{R2}(μA) @ V_R=3.5V	V_{BR} (V) @ I_T (Note 2)		I_T	V_C (V) @ I_{PP} = 1 A (Note 3)	V_C (V) @MAX I_{PP} (Note 3)	I_{PP}(A) (Note 3)	P_{PK}(W) (Note 3)	C (pF)
	Max	Max	Max	Min	Max	mA	Max	Max	Max	Max	Max
TESDN051BD82	5.0	0.5	0.3	5.6	8.0	1.0	9.8	12.5	5.5	69	15

Other voltage available upon request.

2. V_{BR} is measured with a pulse test current IT at an ambient temperature of 25

3. Surge current waveform per Figure 3.

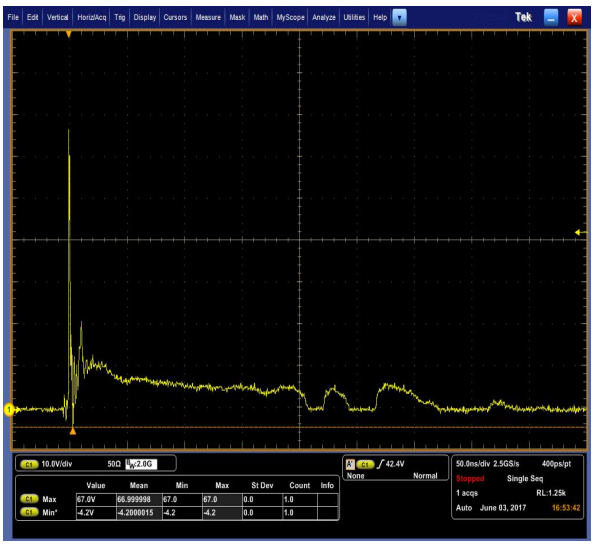


Fig1. ESD Clamping Voltage Screenshot
Positive 8 kV Contact per IEC61000-4-2

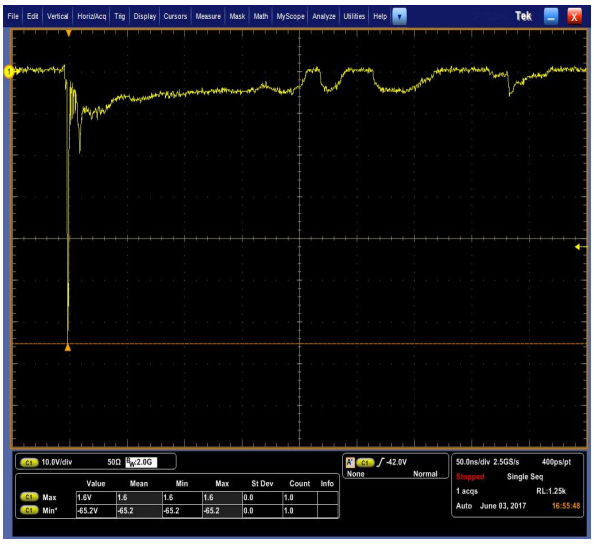


Fig2. ESD Clamping Voltage Screenshot
Negative 8 kV Contact per IEC61000-4-2

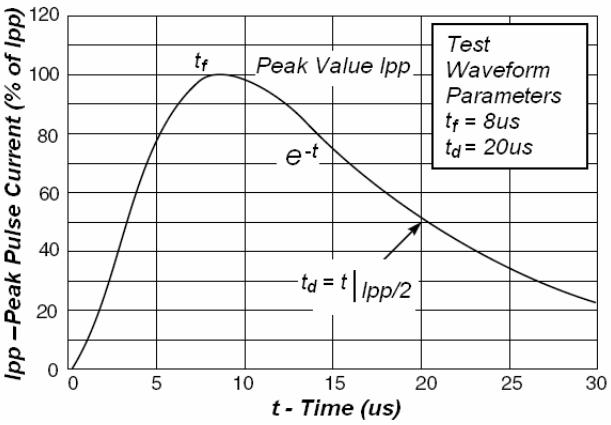


Fig3. Pulse Waveform

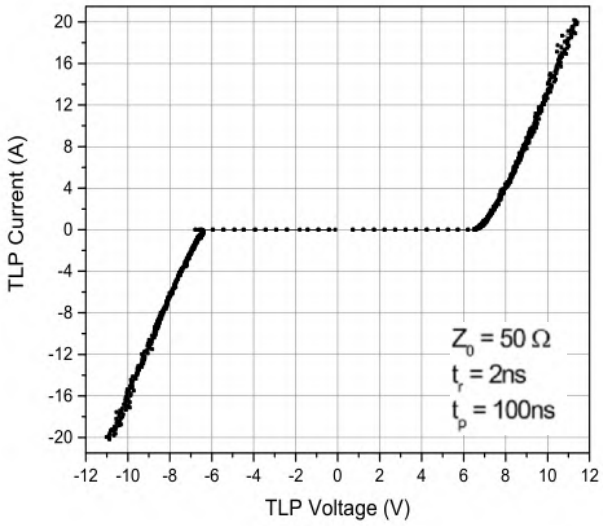
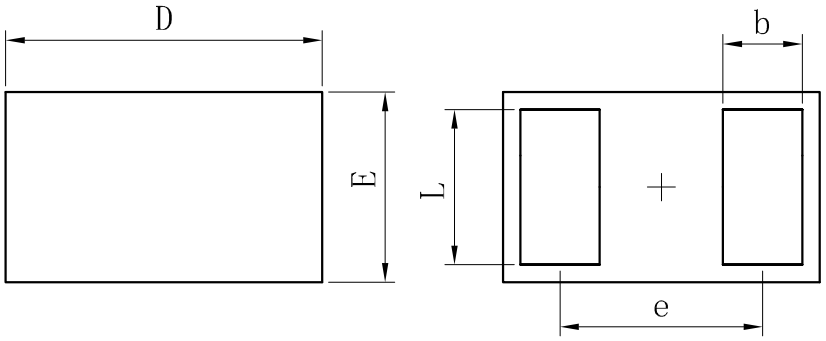
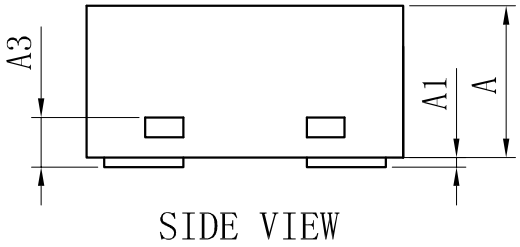


Fig4.TLP Measurement

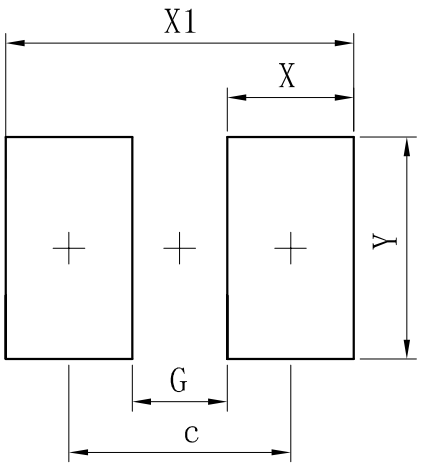
OUTLINE AND DIMENSIONS



SOD882			
Dim	Min	Typ	Max
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e	-	0.64	-
L	0.44	0.49	0.54
b	0.20	0.25	0.30
A	0.43	0.48	0.53
A1	0	-	0.05
A3	0.127REF.		
All Dimensions in mm			



SOLDERING FOOTPRINT



Dimensions	(mm)
c	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

NOTICE

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